

FEATURES

- **LOW INTERMODULATION DISTORTION** ■ **HIGH GAIN**
 IM3=-45 dBc at Pout= 36.5dBm G1dB=9.5dB at 4.4GHz to 5.0GHz
 Single Carrier Level
- **HIGH POWER** ■ **BROAD BAND INTERNALLY MATCHED**
 P1dB=48.0dBm at 4.4GHz to 5.0GHz ■ **HERMETICALLY SEALED PACKAGE**

RF PERFORMANCE SPECIFICATIONS (Ta= 25° C)

CHARACTERISTICS	SYMBOL	CONDITION	UNIT	MIN.	TYP.	MAX.
Output Power at 1dB Compression Point	P1dB	VDS= 10V f = 4.4 to 5.0GHz IDSset=9.5A	dBm	47.0	48.0	—
Power Gain at 1dB Compression Point	G1dB		dB	8.5	9.5	----
Drain Current	IDS1		A	—	13.2	15.0
Gain Flatness	ΔG		dB	—	—	±0.8
Power Added Efficiency	ηadd		%	—	41	—
3rd Order Intermodulation Distortion	IM3	Two Tone Test Po=36.5dBm (Single Carrier Level)	dBc	-42	-45	—
Drain Current	IDS2		A	----	13.2	15.0
Channel Temperature Rise	ΔTch	VDS X IDS X Rth(c-c)	°C	—	—	90

Recommended Gate Resistance(Rg) : 28 Ω (Max.)

ELECTRICAL CHARACTERISTICS (Ta= 25° C)

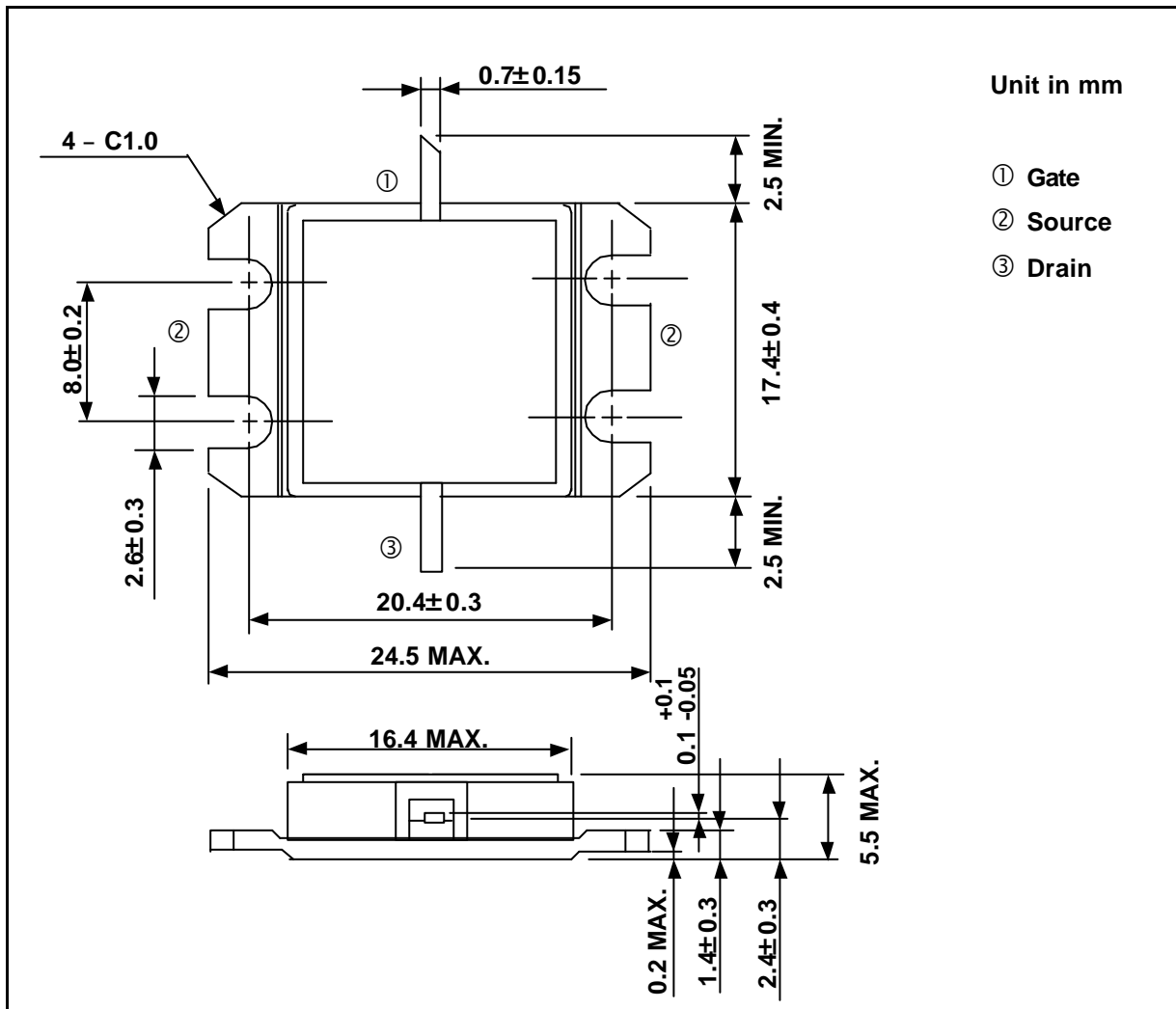
CHARACTERISTICS	SYMBOL	CONDITION	UNIT	MIN.	TYP.	MAX.
Transconductance	gm	VDS= 3V IDS= 12.0A	S	—	20	—
Pinch-off Voltage	VGSoff	VDS= 3V IDS= 200mA	V	-1.0	-1.8	-3.0
Saturated Drain Current	IDSS	VDS= 3V VGS= 0V	A	—	38	46
Gate-Source Breakdown Voltage	VGSO	IGS= -1.0mA	V	-5	—	—
Thermal Resistance	Rth(c-c)	Channel to Case	°C/W	—	0.6	0.8

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ABSOLUTE MAXIMUM RATINGS (Ta= 25° C)

CHARACTERISTICS	SYMBOL	UNIT	RATING
Drain-Source Voltage	V _{DS}	V	15
Gate-Source Voltage	V _{GS}	V	-5
Drain Current	I _{DS}	A	26
Total Power Dissipation (T _c = 25 °C)	P _T	W	215
Channel Temperature	T _{ch}	°C	175
Storage Temperature	T _{stg}	°C	-65 to +175

PACKAGE OUTLINE (2-16G1B)**HANDLING PRECAUTIONS FOR PACKAGED TYPE**

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260° C.